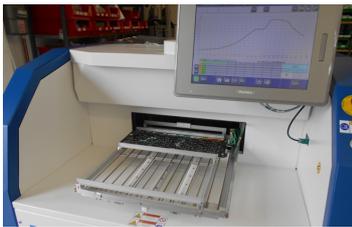
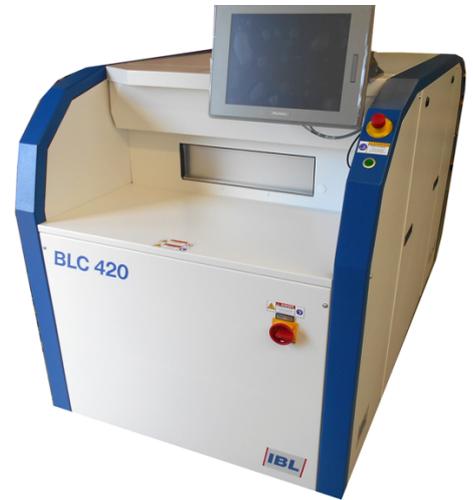


Premium Batch Reflow Vapour Phase Soldering Oven

The BLC-Series is an environmentally friendly and flexible system for high quality soldering. With the premium series the most complex soldering applications can be easily mastered. A high mix of large and small components can simultaneously get soldered without overheating any of them. The Intelligent Profiling System gives the user full control of temperature rise to reach the best soldering profiles. Together with the unique patented Soft Vapour Control there is no fear of exceeding temperature increase rates of components. Their outstanding low energy consumption and exhaust air volume compared to other soldering systems result in even lower running costs. Excellent heat transfer in an inert oxygen free atmosphere without the need of costly nitrogen. Double chamber system with a large user-friendly touch display makes this machine user friendly, easy to set up and use. Soldering is possible regardless of assembly weight with the same profile.



Ready for loading



Transport of boards into the process chamber



Observation window

Features:

- Comfortable 15" Touch-Screen-PC
- Permanent data collection
- Unlimited program memory with a large amount of sample programs
- Network capable
- Password protected operation levels
- Energy management system
- Intelligent Profiling System (IPS)
- Automatic loading and unloading of the Work Piece Carrier
- Patented vibration and maintenance free transport system
- Double chamber design and medium recovery results in a very low fluid consumption
- Fluid level control and automatic filtering
- Integrated cooling fans
- Minimal maintenance and wear due to all moving parts mounted outside of the process chamber
- Easy access to solder chamber for cleaning and maintenance purposes
- Observation window into the solder chamber
- Exhaust connection
- Cool handling – transport system in cool area

Options:

Process extensions

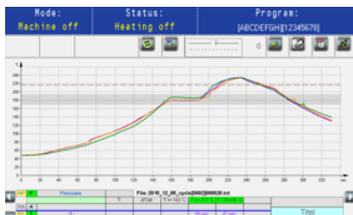
- Nitrogen venting of the cooling and process chamber
- Infrared heating
- Variety of options for pcb cooling
- Patented Rapid Cooling System (RCS)
- Up to 3 temperature measurement channels
- Scanner options for easy, fast and safe operation enabling automatic program change
- Multi-Level Mode for rapid switching between different soldering heights within the vapour blanket thus enabling controlled heat development of small against large volume components

Software extensions

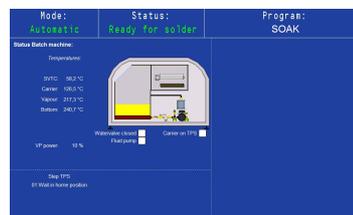
- Online Temperature Recording Software (TRS) for data analysis and storage including alarm and event log
- Pilot mode for easy temperature-controlled soldering and setting up of profiles
- Heating power monitoring
- Robot interface
- Barcode system for automatic program change and traceability, ready for Industry 4.0

Hardware extensions

- Adapter for double sided boards
- Stain-less steel grid for batch carrier
- Work piece carrier for double sided boards
- Heavy Duty HD model for loads up to 14kg with stronger heating capabilities
- Exhaust system expansions
- 2nd Emergency Stop
- Signal light tower
- UPS – Uninterruptable Power Supply
- ReSy – a device for repair of QFPs and BGAs
- Chiller for inside or outside use



Profile monitoring



Machine status



Scanner option

Technical data:

	BLC420	BLC620	BLC820
Width	1060 mm (41.73")	1260 mm (49.61")	1460 mm (57.48")
Depth	1960 mm (77.17")		
Height	1320 mm (51.97")		
Weight	520 kg ()	650 kg (1433 lbs)	780 kg (1719.61 lbs)
Max. PCB size	450 x 540 x 80 mm (17.72 x 21.26 x 3.15")	650 x 540 x 80 mm (25.59 x 21.26 x 3.15")	850 x 540 x 80 mm (33.46 x 21.26 x 3.15")
Max. load on single carrier	7 kg (15.43 lbs)		
Liquid agent filling	15 kg (33.07 lbs)	20 kg (44.10 lbs)	25 kg (55.12 lbs)
Water connection	1/2" / 2,5 – 5 bar		
Max. heating capacity	6,4 kW	7,8 kW	10,4 kW
Average power consumption	2,6 kW/h	3,2 kW/h	3,6 kW
Power supply	400 / 230 VAC, 50/60Hz		
Main fuse	16A „gl“ or „C“		20A „gl“ or „C“

Specifications subject to change without prior notice

D1E11-BLC420/620/820 -E- 210322